



## ORDER DESCRIPTION

### 1. Object of the contract

The subject of the order is the supply of

No	Product name	Qty [pcs.]
1	InP Wafers N-type 3"	84

### 1. Parameters

Product name		Parameter	Specification
<b>InP Wafers N-type 3"</b>	Diameter 3" Thickness: 625±25 µm Diameter: 76.2±0.3 mm	Primary Flat	EJ (0-1-1) ±0.02°
		Carrier Conc.:	Min 1E18 [cm <sup>3</sup> ]
		Mobility:	min 1000 [cm <sup>2</sup> /Vs]
		EPD (Average):	Max 500 [cm <sup>2</sup> ]
		Surface Finish:	SSP (single side polished) Side 1: Polished Side 2: Etched
		Packaging:	ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room.